

# MOSFET – Power, N-Channel, Ultrafet

100 V, 56 A, 25 mΩ

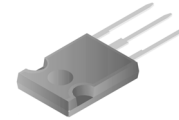
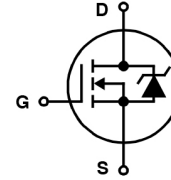
## HUF75639G3, HUF75639P3, HUF75639S3S, HUF75639S3

These N-Channel power MOSFETs are manufactured using the innovative Ultrafet process. This advanced process technology achieves the lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching converters, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.

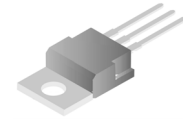
Formerly developmental type TA75639.

### Features

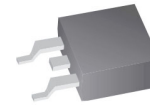
- 56 A, 100 V
- Simulation Models
  - ◆ Temperature Compensated PSPICE® and SABER™ Electrical Models
  - ◆ Spice and Saber Thermal Impedance Models
  - ◆ [www.onsemi.com](http://www.onsemi.com)
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Related Literature
  - ◆ TB334, “Guidelines for Soldering Surface Mount Components to PC Boards”
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



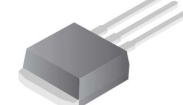
TO-247-3LD  
CASE 340CK



TO-220-3LD  
CASE 340AT

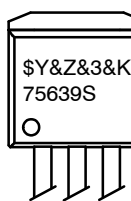
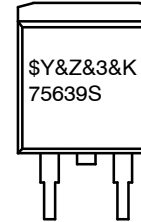
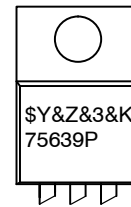
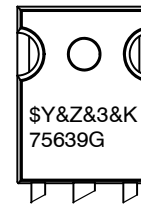


D2PAK-3  
CASE 418AJ



I2PAK  
CASE 418AV

### MARKING DIAGRAMS



- |        |                                 |
|--------|---------------------------------|
| &Y     | = onsemi Logo                   |
| &Z     | = Assembly Plant Code           |
| &3     | = 3-Digit Date Code             |
| &K     | = 2-Digit Lot Traceability Code |
| 75639x | = Specific Device Code          |
| x      | = G/P/S                         |

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

# HUF75639G3, HUF75639P3, HUF75639S3S, HUF75639S3

## ORDERING INFORMATION

PART NUMBER	PACKAGE	BRAND
HUF75639G3	TO-247	75639G
HUF75639P3	TO-220AB	75639P
HUF75639S3ST	TO-263AB	75639S
HUF75639S3	TO-262AA	75639S

## PACKAGING

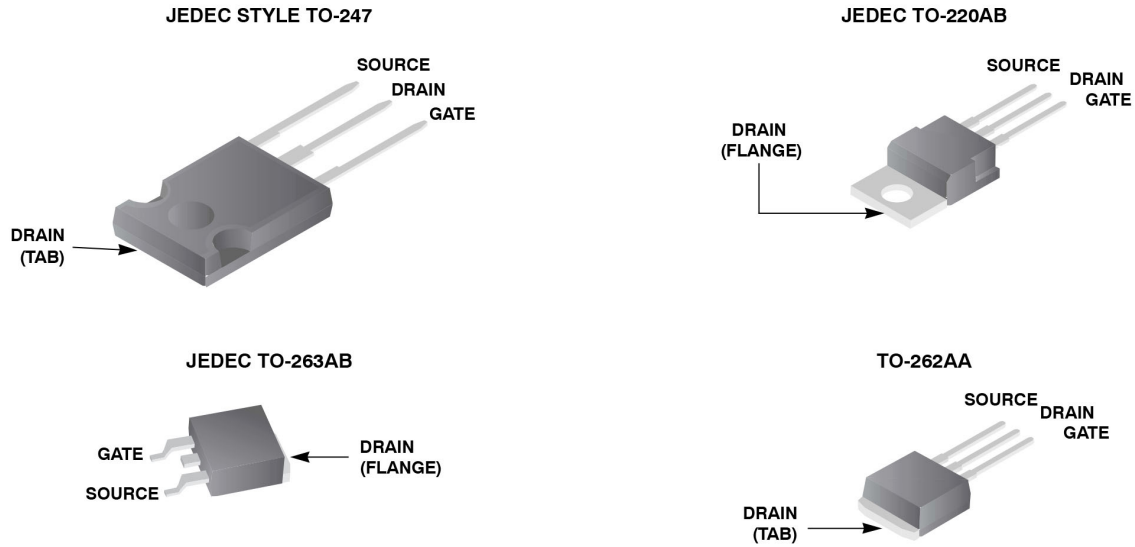


Figure 1.

## ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise specified

Description	Symbol	Ratings	Units
Drain to Source Voltage (Note 1)	$V_{DSS}$	100 V	V
Drain to Gate Voltage ( $R_{GS} = 20\text{ k}\Omega$ ) (Note 1)	$V_{DGR}$	100 V	V
Gate to Source Voltage	$V_{GS}$	$\pm 20\text{ V}$	V
Drain Current Continuous (Figure 2) Pulsed Drain Current	$I_D$ $I_{DM}$	56 Figure 4	A
Pulsed Avalanche Rating	$E_{AS}$	Figures 6, 14, 15	
Power Dissipation Derate Above $25^\circ\text{C}$	$P_D$	200 1.35	W W/ $^\circ\text{C}$
Operating and Storage Temperature	$T_J, T_{STG}$	$-55\text{ to }175^\circ\text{C}$	$^\circ\text{C}$
Maximum Temperature for Soldering Leads at 0.063in (1.6 mm) from Case for 10s Package Body for 10 s, See Techbrief 334	$T_L$ $T_{pkg}$	300 260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $T_J = 25^\circ\text{C}$  to  $150^\circ\text{C}$ .

# HUF75639G3, HUF75639P3, HUF75639S3S, HUF75639S3

ELECTRICAL SPECIFICATION  $T_J = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
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## OFF STATE SPECIFICATIONS

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\ \mu\text{A}$ , $V_{GS} = 0\ \text{V}$ (Figure 11)	100	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 95\ \text{V}$ , $V_{GS} = 0\ \text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 90\ \text{V}$ , $V_{GS} = 0\ \text{V}$ , $T_C = 150^\circ\text{C}$	-	-	250	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\ \text{V}$	-	-	$\pm 100$	nA

## ON STATE SPECIFICATIONS

$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\ \mu\text{A}$ (Figure 10)	2	-	4	V
$R_{DS(on)}$	Drain to Source On Resistance	$I_D = 56\ \text{A}$ , $V_{GS} = 10\ \text{V}$ (Figure 9)	-	21	25	m $\Omega$

## THERMAL SPECIFICATIONS

$R_{\theta JC}$	Thermal Resistance Junction to Case	(Figure 3)	-	-	0.74	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-247	-	-	30	$^\circ\text{C}/\text{W}$
		TO-220, TO-263, TO-262	-	-	62	$^\circ\text{C}/\text{W}$

## SWITCHING SPECIFICATIONS ( $V_{GS} = 10\ \text{V}$ )

$t_{ON}$	Turn-On Time	$V_{DD} = 50\ \text{V}$ , $I_D \cong 56\ \text{A}$ , $R_L = 0.89\ \Omega$ , $V_{GS} = 10\ \text{V}$ , $R_{GS} = 5.1\ \Omega$	-	-	110	ns
$t_{d(ON)}$	Turn-On Delay Time		-	15	-	ns
$t_r$	Rise Time		-	60	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time		-	20	-	ns
$t_f$	Fall Time		-	25	-	ns
$t_{OFF}$	Turn-Off Time		-	-	70	ns

## GATE CHARGE SPECIFICATIONS

$Q_g(TOT)$	Total Gate Charge	$V_{GS} = 0\ \text{V}$ to $20\ \text{V}$	$V_{DD} = 50\ \text{V}$ , $I_D \cong 56\ \text{A}$ , $R_L = 0.89\ \Omega$ , $I_{g(REF)} = 1.0\ \text{mA}$ (Figure 13)	-	110	130	nC
$Q_g(10)$	Gate Charge at 10 V	$V_{GS} = 0\ \text{V}$ to $10\ \text{V}$		-	57	75	nC
$Q_g(TH)$	Threshold Gate Charge	$V_{GS} = 0\ \text{V}$ to $2\ \text{V}$		-	3.7	4.5	nC
$Q_{gs}$	Gate to Source Gate Charge			-	9.8	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	24	-	nC

## CAPACITANCE SPECIFICATIONS

$C_{ISS}$	Input Capacitance	$V_{DS} = 25\ \text{V}$ , $V_{GS} = 0\ \text{V}$ , $f = 1\ \text{MHz}$ (Figure 12)	-	2000	-	pF
$C_{OSS}$	Output Capacitance		-	500	-	pF
$C_{RSS}$	Reverse Transfer Capacitance		-	65	-	pF

## SOURCE TO DRAIN DIODE SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 56\ \text{A}$	-	-	1.25	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 56\ \text{A}$ , $dI_{SD}/dt = 100\ \text{A}/\mu\text{s}$	-	-	110	ns
Reverse Recovered Charge	$Q_{RR}$	$I_{SD} = 56\ \text{A}$ , $dI_{SD}/dt = 100\ \text{A}/\mu\text{s}$	-	-	320	nC

TYPICAL PERFORMANCE CURVES

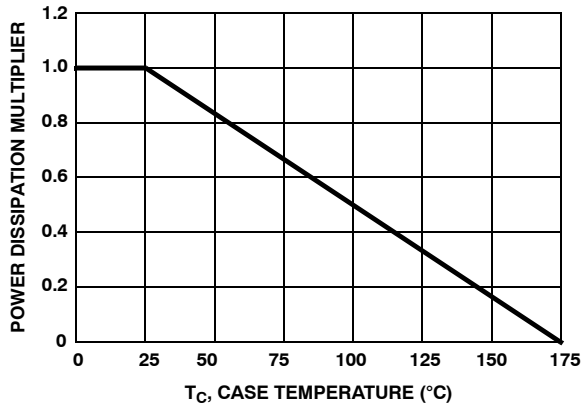


Figure 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

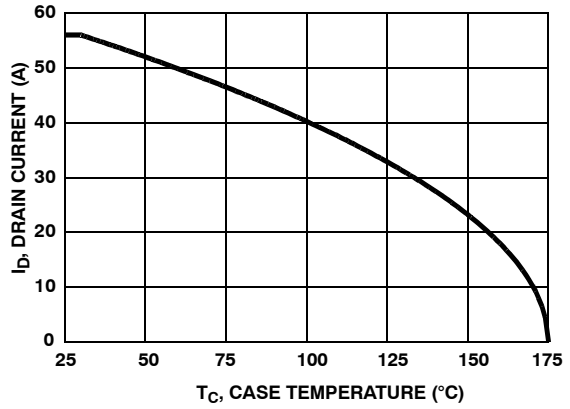


Figure 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

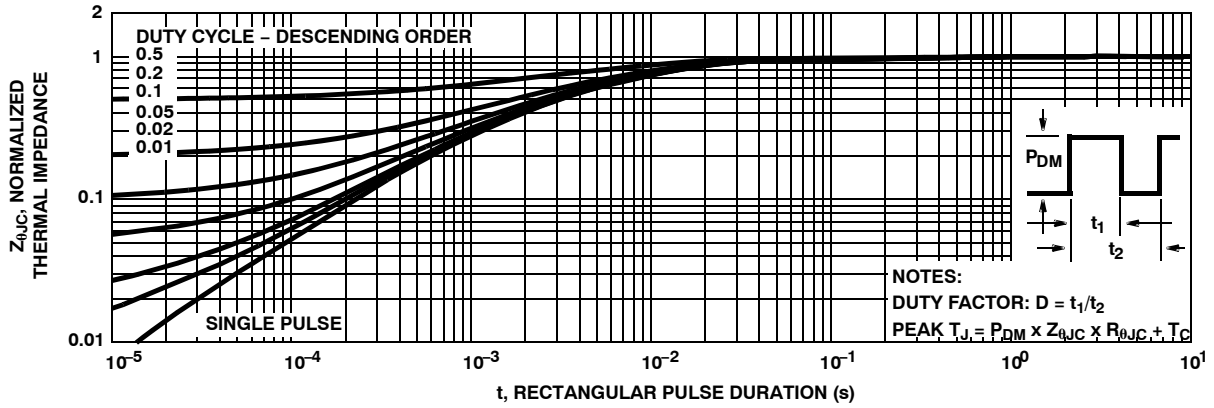


Figure 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

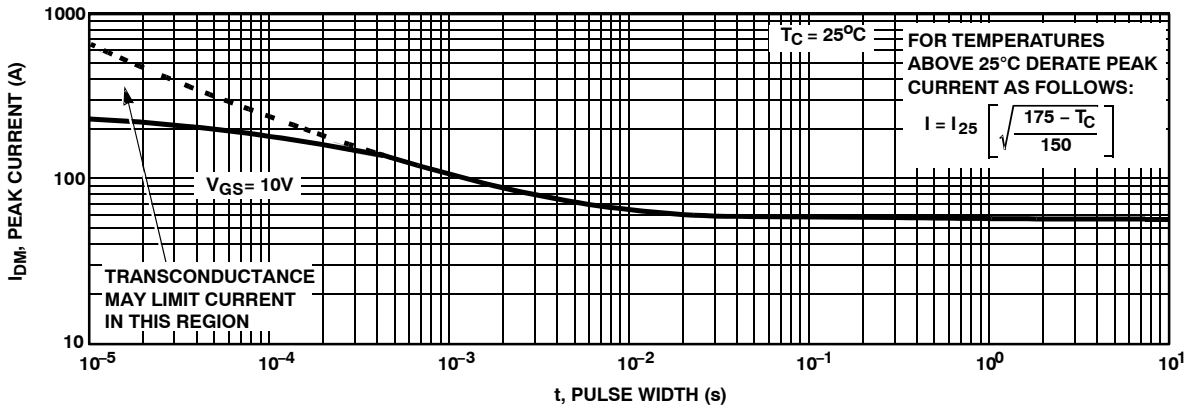


Figure 4. PEAK CURRENT CAPABILITY

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

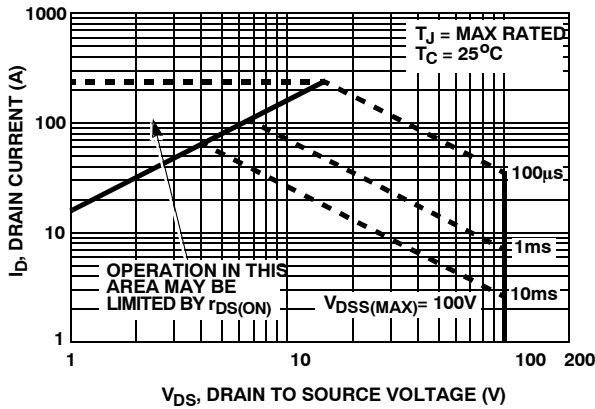


Figure 5. FORWARD BIAS SAFE OPERATING AREA

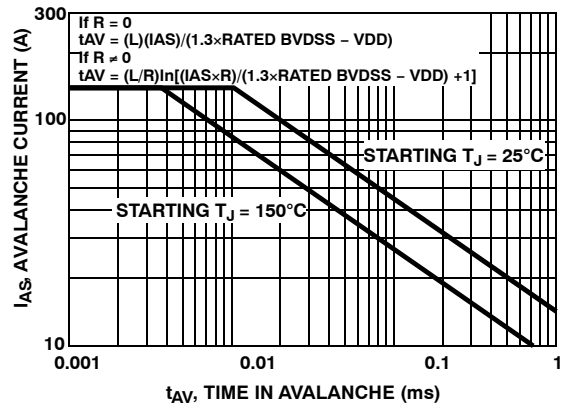


Figure 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

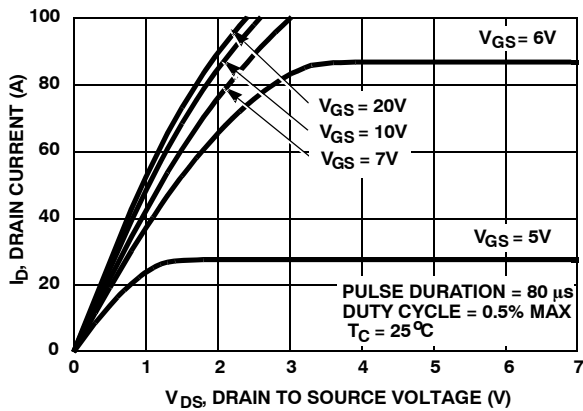


Figure 7. SATURATION CHARACTERISTICS

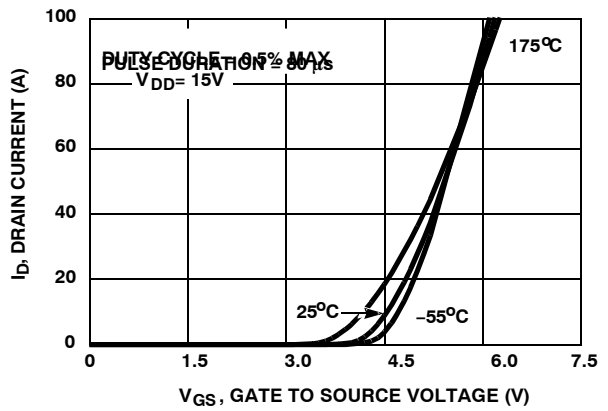


Figure 8. TRANSFER CHARACTERISTICS

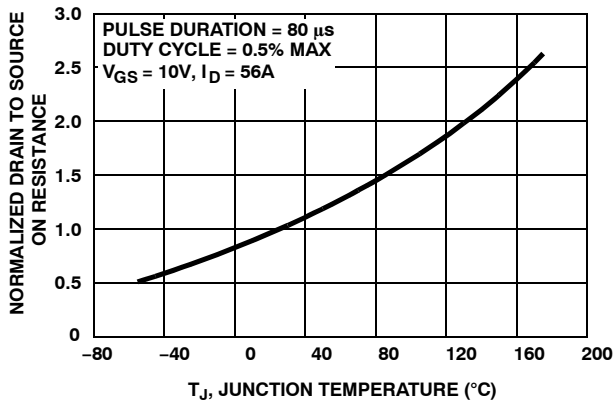


Figure 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

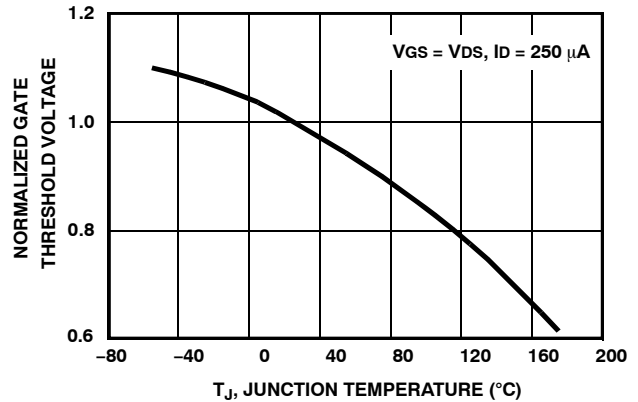


Figure 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

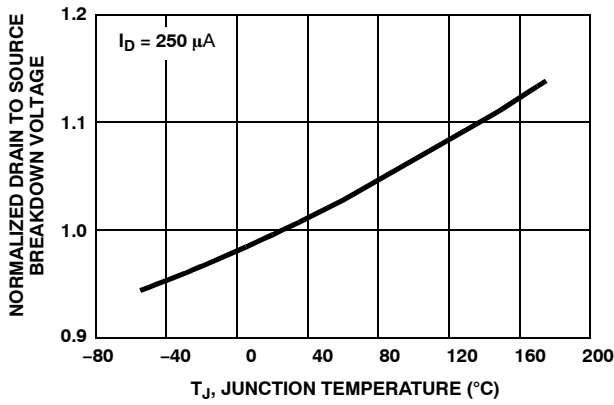


Figure 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

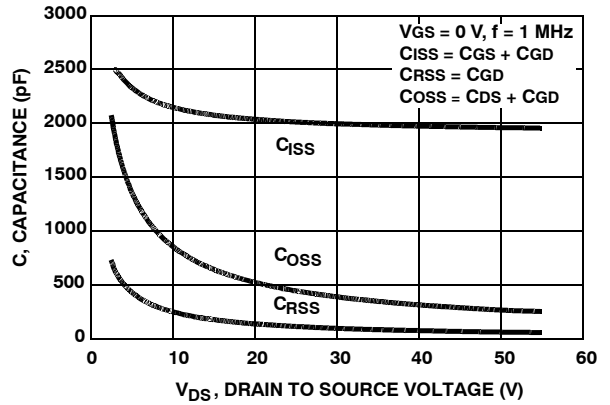


Figure 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

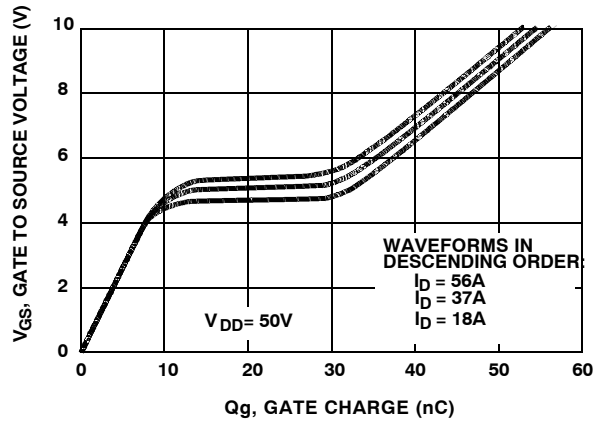


Figure 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

TEST CIRCUITS AND WAVEFORMS

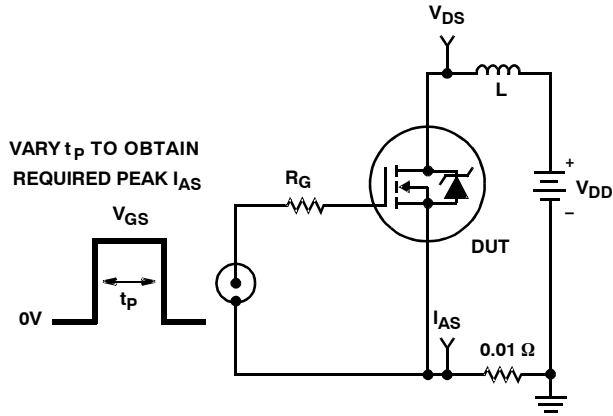


Figure 14. UNCLAMPED ENERGY TEST CIRCUIT

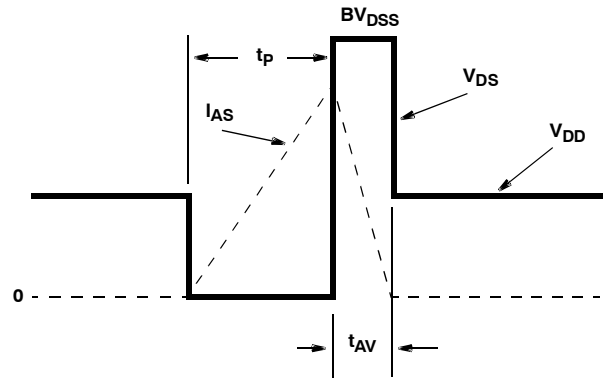


Figure 15. UNCLAMPED ENERGY WAVEFORMS

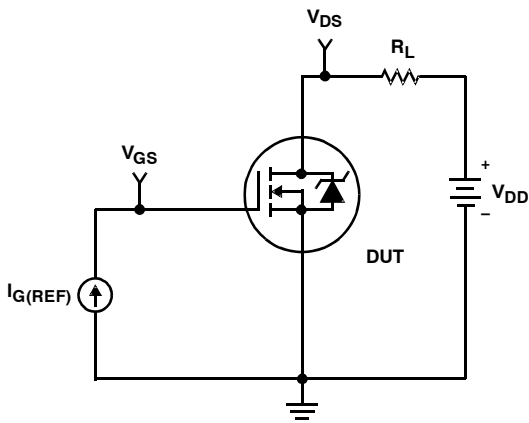


Figure 16. GATE CHARGE TEST CIRCUIT

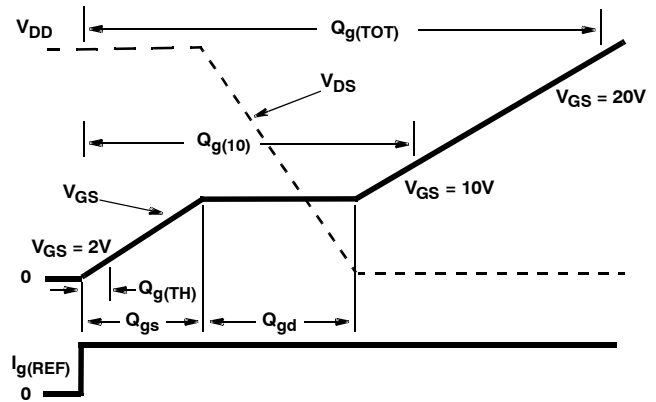


Figure 17. GATE CHARGE WAVEFORM

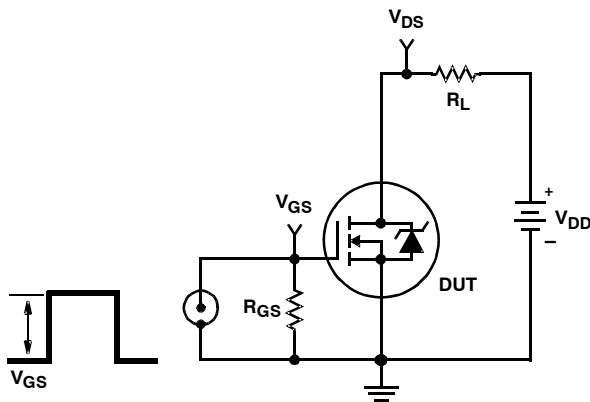


Figure 18. SWITCHING TIME TEST CIRCUIT

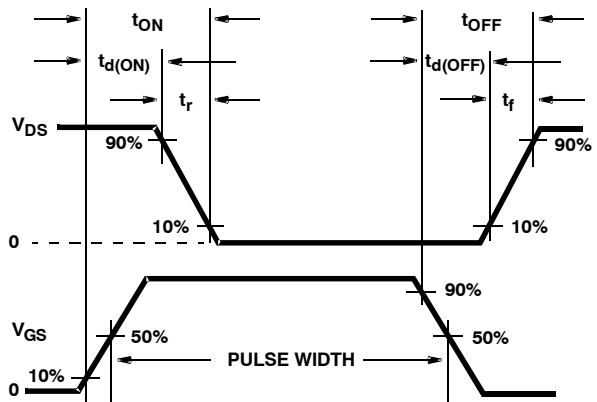


Figure 19. RESISTIVE SWITCHING WAVEFORMS

# HUF75639G3, HUF75639P3, HUF75639S3S, HUF75639S3

## PSPICE Electrical Model

SUBCKT HUF75639 2 1 3 ; rev Oct. 98  
 CA 12 8 2.8e-9  
 CB 15 14 2.65e-9  
 CIN 6 8 1.9e-9

DBODY 7 5 DBODYMOD  
 DBREAK 5 11 DBREAKMOD  
 DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 110  
 EDS 14 8 5 8 1  
 EGS 13 8 6 8 1  
 ESG 6 10 6 8 1  
 EVTHRES 6 21 19 8 1  
 EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 2e-9  
 LGATE 1 9 1e-9  
 LSOURCE 3 7 0.47e-9  
 RLGATE 1 9 10  
 RLDRAIN 2 5 20  
 RLSOURCE 3 7 4.69

MMED 16 6 8 8 MMEDMOD  
 MSTRO 16 6 8 8 MSTROMOD  
 MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1  
 RDRAIN 50 16 RDRAINMOD 1.3e-2  
 RGATE 9 20 0.7  
 RSLC1 5 51 RSLCMOD 1e-6  
 RSLC2 5 50 1e3  
 RSOURCE 8 7 RSOURCEMOD 4.5e-3  
 RVTHRES 22 8 RVTHRESMOD 1  
 RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD  
 S1B 13 12 13 8 S1BMOD  
 S2A 6 15 14 13 S2AMOD  
 S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

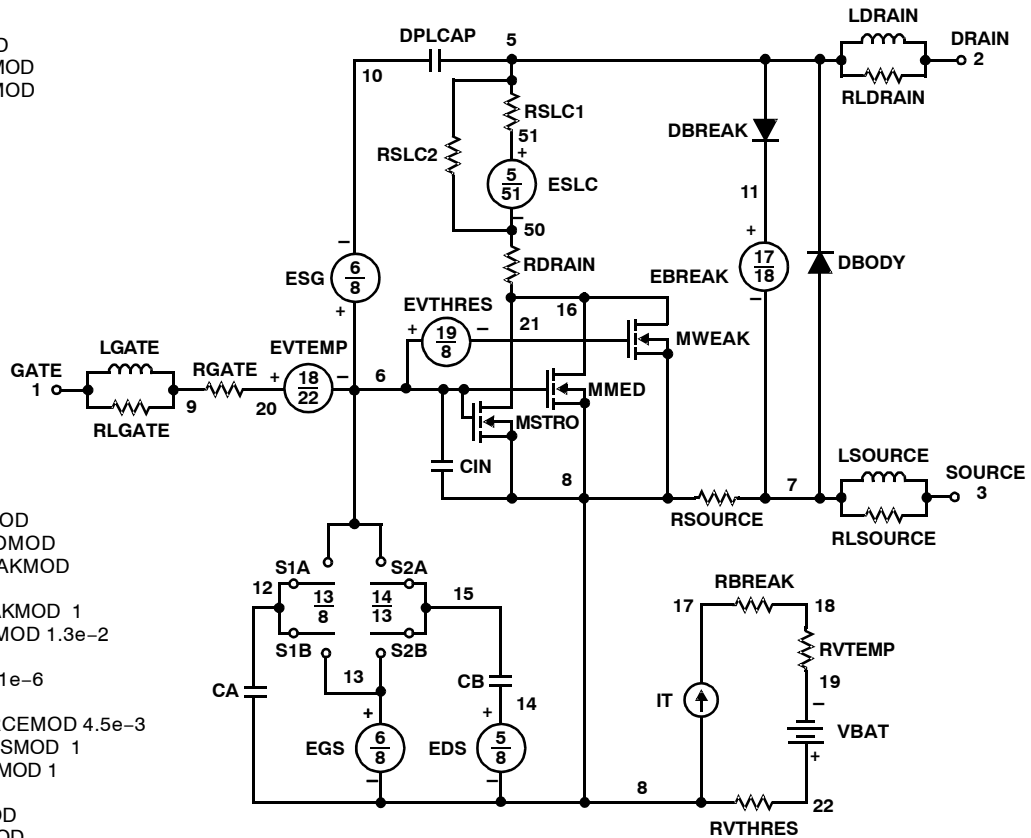
ESLC 51 50 VALUE = {(V(5,51)/ABS(V(5,51)))\*(PWR(V(5,51))/(1e-6\*115),4)}

.MODEL DBODYMOD D (IS = 1.4e-12 RS = 3.3e-3 XTI = 4.7 TRS1 = 2e-3 TRS2 = 0.1e-5 CJO = 3.3e-9 TT = 6.1e-8 M = 0.7)  
 .MODEL DBREAKMOD D (RS = 3.5e-1 TRS1 = 1e-3 TRS2 = 1e-6)  
 .MODEL DPLCAPMOD D (CJO = 2.2e-9 IS = 1e-3 ON = 10 M = 0.95 vj = 1.0)  
 .MODEL MMEDMOD NMOS (VTO = 3.5 KP = 4.8 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u Rg = 0.7)  
 .MODEL MSTROMOD NMOS (VTO = 3.97 KP = 56.5 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)  
 .MODEL MWEAKMOD NMOS (VTO = 3.11 KP = 0.085 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 7 RS = 0.1)  
 .MODEL RBREAKMOD RES (TC1 = 0.8e-3 TC2 = 1e-6)  
 .MODEL RDRAINMOD RES (TC1 = 1e-2 TC2 = 1.75e-5)  
 .MODEL RSLCMOD RES (TC1 = 2.8e-3 TC2 = 14e-6)  
 .MODEL RSOURCEMOD RES (TC1 = 0 TC2 = 0)  
 .MODEL RVTHRESMOD RES (TC = -2.0e-3 TC2 = -1.75e-5)  
 .MODEL RVTEMPMOD RES (TC1 = -2.75e-3 TC2 = 0.05e-9)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -6.0 VOFF = -3.5)  
 .MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -3.5 VOFF = -6.0)  
 .MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.5 VOFF = 4.95)  
 .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 4.95 VOFF = -2.5)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.





**SABER Electrical Model**

nom temp=25 deg c 100v Ultrafet

REV Oct. 98

template huf75639 n2,n1,n3  
electrical n2,n1,n3

```

{
var i iscl
d..model dbodymod = (is=1.4e-12, xti=4.7, cjo=33e-10, tt=6.1e-8, m=0.7)
d..model dbreakmod = ()
d..model dplcapmod = (cjo=22e-10, is=1e-30, n=10, m=0.95, vj=1.0)
m..model mmedmod = (type=_n, vto=3.5, kp=4.8, is=1e-30, tox=1)
m..model mstrongmod = (type=_n, vto=3.97, kp=56.5, is=1e-30, tox=1)
m..model mweakmod = (type=_n, vto=3.11, kp=0.085, is=1e-30, tox=1)
sw_vcsp..model s1amod = (ron=1e-5, roff=0.1, von=-6.0, voff=-3.5)
sw_vcsp..model s1bmod = (ron=1e-5, roff=0.1, von=-3.5, voff=-6.0)
sw_vcsp..model s2amod = (ron=1e-5, roff=0.1, von=-2.5, voff=4.95)
sw_vcsp..model s2bmod = (ron=1e-5, roff=0.1, von=4.95, voff=-2.5)
    
```

```

c.ca n12 n8 = 28.5e-10
c.cb n15 n14 = 26.5e-10
c.cin n6 n8 = 19e-10
    
```

```

d.dbody n7 n71 = model=dbodymod
d.dbreak n72 n11 = model=dbreakmod
d.dplcap n10 n5 = model=dplcapmod
    
```

```
i.it n8 n17 = 1
```

```

l.ldrain n2 n5 = 2.0e-9
l.lgate n1 n9 = 1e-9
l.lsource n3 n7 = 4.69e-10
    
```

```

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u
    
```

```

res.rbreak n17 n18 = 1, tc1=0.8e-3, tc2=-1e-6
res.rbody n71 n5 = 3.3e-3, tc1=2.0e-3, tc2=0.1e-5
res.rdbreak n72 n5 = 3.5e-1, tc1=1e-3, tc2=1e-6
res.rdrain n50 n16 = 13e-3, tc1=1e-2, tc2=1.75e-5
res.rgate n9 n20 = 0.7
res.rldrain n2 n5 = 20
res.rlgate n1 n9 = 10
res.rlsource n3 n7 = 4.69
res.rslc1 n5 n51 = 1e-6, tc1=2.8e-3, tc2=14e-6
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 4.5e-3, tc1=0, tc2=0
res.rvtemp n18 n19 = 1, tc1=-2.75e-3, tc2=0.05e-9
res.rvthres n22 n8 = 1, tc1=-2e-3, tc2=-1.75e-5
    
```

```

spe.ebreak n11 n7 n17 n18 = 110
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1
    
```

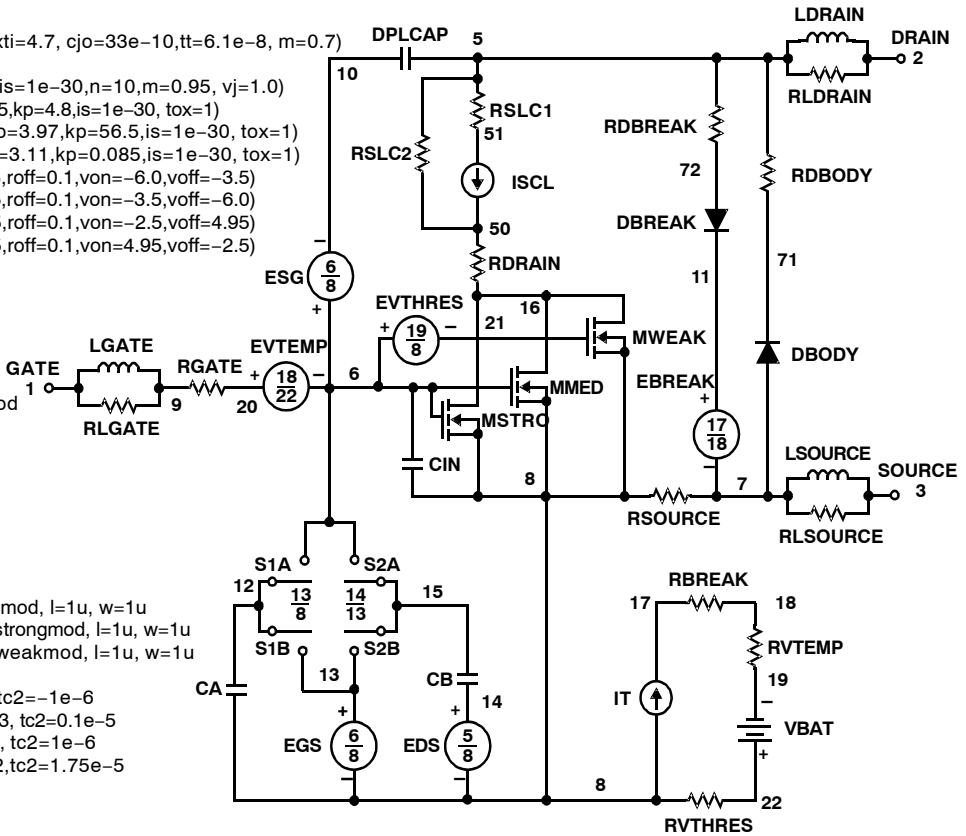
```

sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod
    
```

```
v.vbat n22 n19 = dc=1
```

```

equations {
i (n51->n50) += iscl
iscl: v(n51, n50) = ((v(n5, n51)/(1e-9+abs(v(n5, n51))))*((abs(v(n5, n51))*1e6/115))** 4)
}
}
    
```



### Spice Thermal Model

REV APRIL 1998

HUF75639

CTHERM1 TH 6 2.8e-3  
 CTHERM2 6 5 4.6e-3  
 CTHERM3 5 4 5.5e-3  
 CTHERM4 4 3 9.2e-3  
 CTHERM5 3 2 1.7e-2  
 CTHERM6 2 TL 4.3e-2

RTHERM1 TH 6 5.0e-4  
 RTHERM2 6 5 1.5e-3  
 RTHERM3 5 4 2.0e-2  
 RTHERM4 4 3 9.0e-2  
 RTHERM5 3 2 1.9e-1  
 RTHERM6 2 TL 2.9e-1

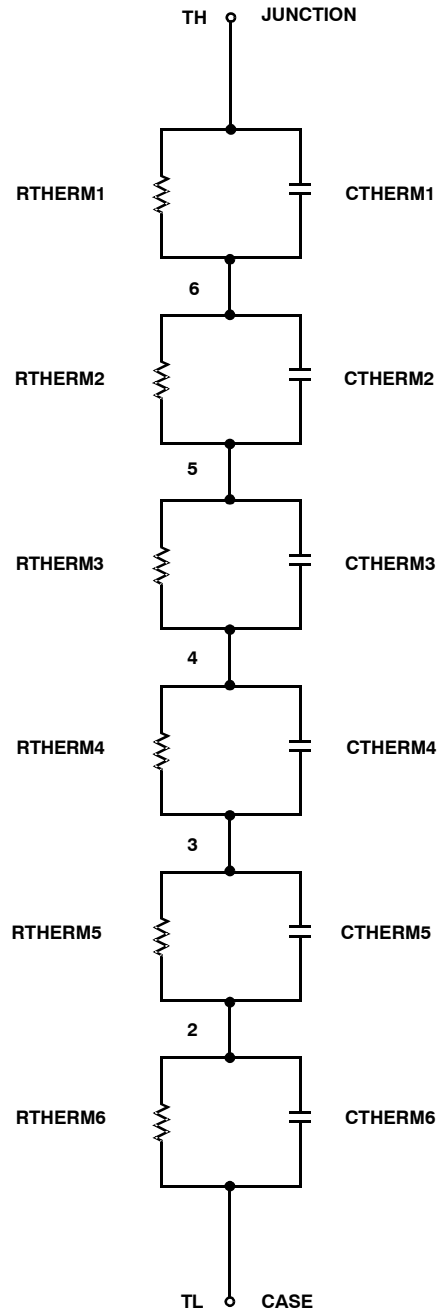
### Saber Thermal Model

Saber thermal model HUF75639

template thermal\_model th tl  
 thermal\_c th, tl

```
{
ctherm.ctherm1 th 6 = 2.8e-3
ctherm.ctherm2 6 5 = 4.6e-3
ctherm.ctherm3 5 4 = 5.5e-3
ctherm.ctherm4 4 3 = 9.2e-3
ctherm.ctherm5 3 2 = 1.7e-2
ctherm.ctherm6 2 tl = 4.3e-2
```

```
rtherm.rtherm1 th 6 = 5.0e-4
rtherm.rtherm2 6 5 = 1.5e-3
rtherm.rtherm3 5 4 = 2.0e-2
rtherm.rtherm4 4 3 = 9.0e-2
rtherm.rtherm5 3 2 = 1.9e-1
rtherm.rtherm6 2 tl = 2.9e-1
}
```

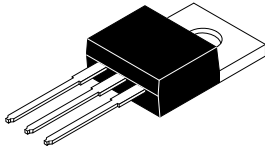


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 Saber is a registered trademark of Sabremark Limited Partnership.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

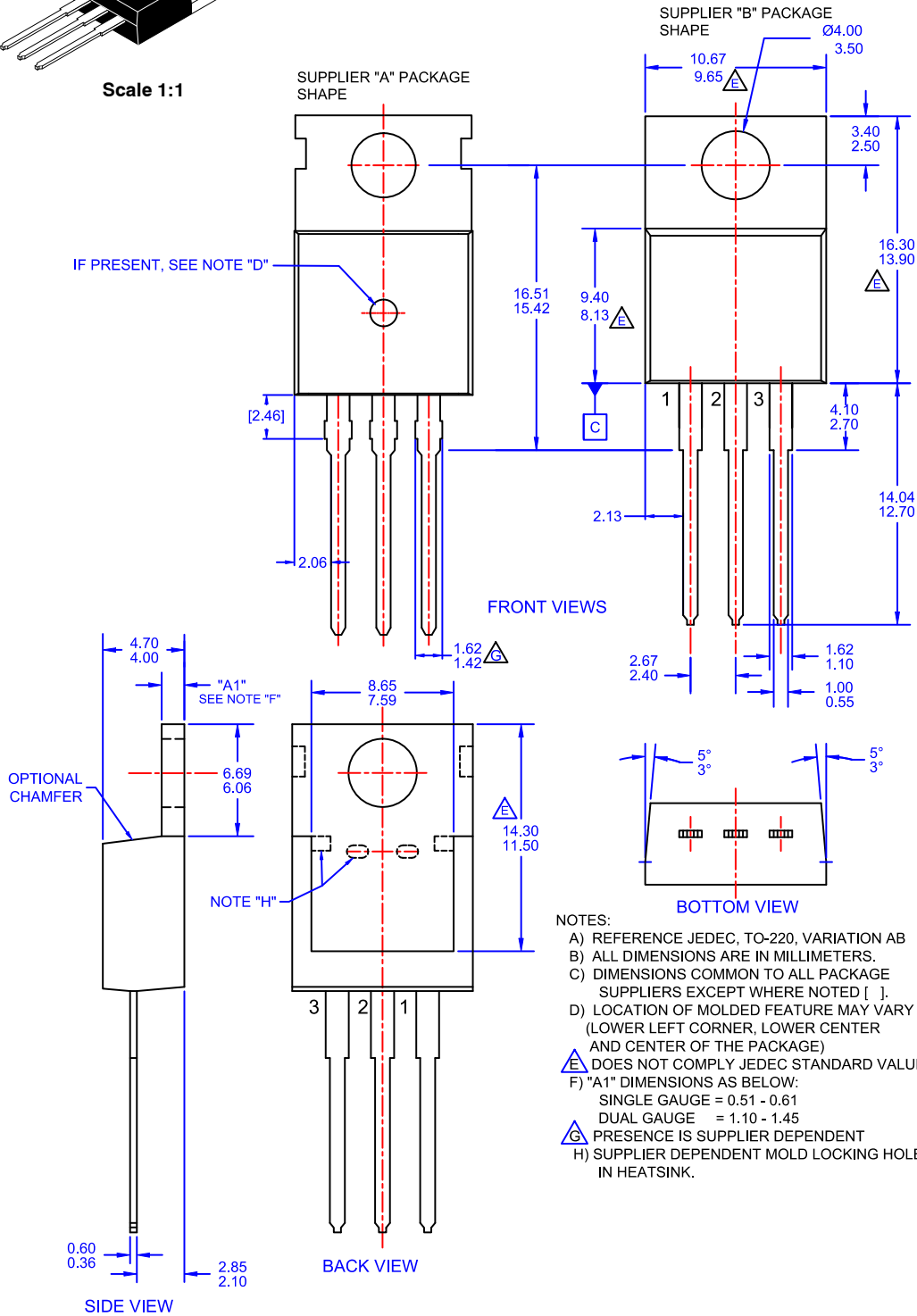
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Scale 1:1

### TO-220-3LD CASE 340AT ISSUE A

DATE 03 OCT 2017



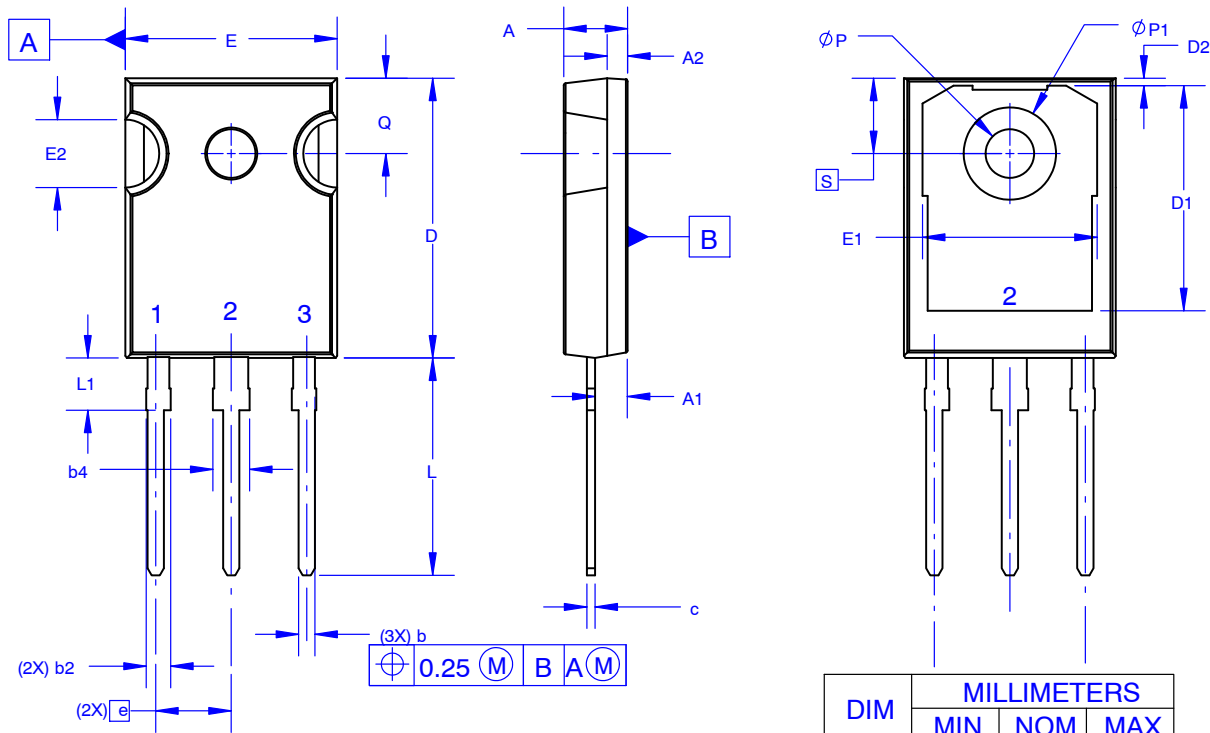
- NOTES:
- A) REFERENCE JEDEC, TO-220, VARIATION AB
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS COMMON TO ALL PACKAGE SUPPLIERS EXCEPT WHERE NOTED [ ].
  - D) LOCATION OF MOLDED FEATURE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE)
  - E) DOES NOT COMPLY JEDEC STANDARD VALUE.
  - F) "A1" DIMENSIONS AS BELOW:  
 SINGLE GAUGE = 0.51 - 0.61  
 DUAL GAUGE = 1.10 - 1.45
  - G) PRESENCE IS SUPPLIER DEPENDENT
  - H) SUPPLIER DEPENDENT MOLD LOCKING HOLES IN HEATSINK.

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<b>DESCRIPTION:</b>	<b>TO-220-3LD</b>	<b>PAGE 1 OF 1</b>

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**TO-247-3LD SHORT LEAD**  
**CASE 340CK**  
**ISSUE A**

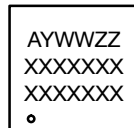
DATE 31 JAN 2019



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 - 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

**GENERIC MARKING DIAGRAM\***



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.40	1.50	1.60
b	1.17	1.26	1.35
b2	1.53	1.65	1.77
b4	2.42	2.54	2.66
c	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	13.08	~	~
D2	0.51	0.93	1.35
E	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
e	~	5.56	~
L	15.75	16.00	16.25
L1	3.69	3.81	3.93
ØP	3.51	3.58	3.65
ØP1	6.60	6.80	7.00
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

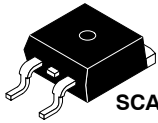
<b>DOCUMENT NUMBER:</b>	<b>98AON13851G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>TO-247-3LD SHORT LEAD</b>	<b>PAGE 1 OF 1</b>

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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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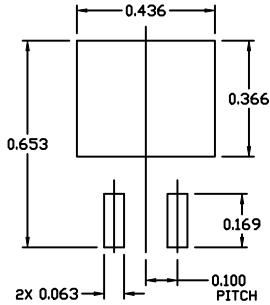
SCALE 1:1

### D<sup>2</sup>PAK-3 (TO-263, 3-LEAD)

#### CASE 418AJ

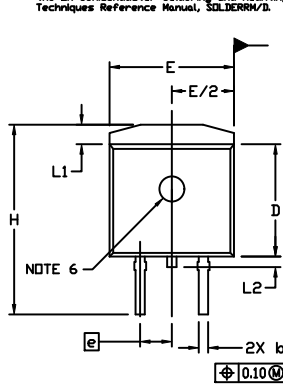
#### ISSUE F

DATE 11 MAR 2021



#### RECOMMENDED MOUNTING FOOTPRINT

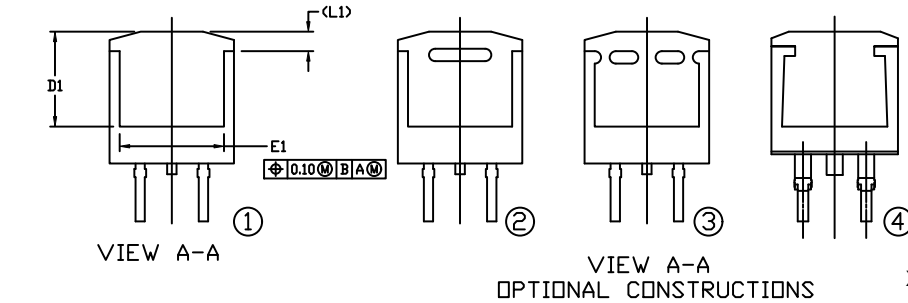
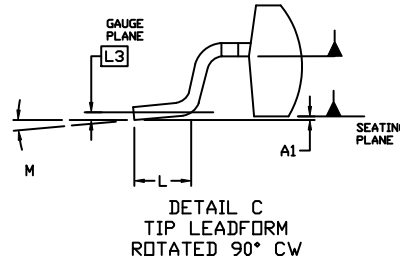
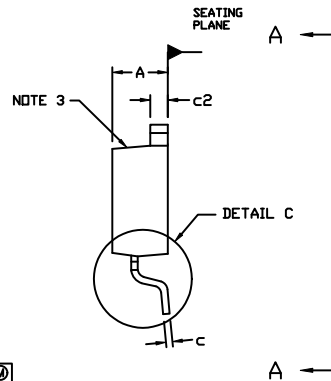
■ For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



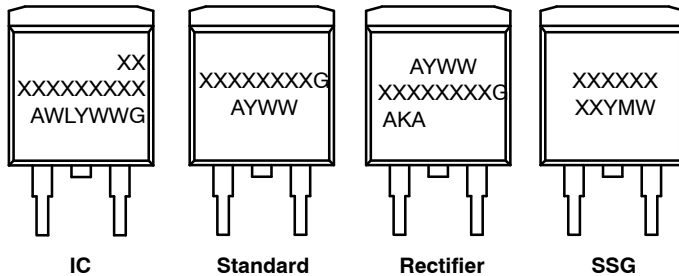
#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: INCHES
3. CHAMFER OPTIONAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1, AND E1.
6. OPTIONAL MOLD FEATURE.
7. Ⓚ, Ⓛ ... OPTIONAL CONSTRUCTION FEATURE CALL OUTS.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
c	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260	---	6.60	---
E	0.380	0.420	9.65	10.67
E1	0.245	---	6.22	---
e	0.100	BSC	2.54	BSC
H	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1	---	0.066	---	1.68
L2	---	0.070	---	1.78
L3	0.010	BSC	0.25	BSC
M	0*	8*	0*	8*



#### GENERIC MARKING DIAGRAMS\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- W = Week Code (SSG)
- M = Month Code (SSG)
- G = Pb-Free Package
- AKA = Polarity Indicator

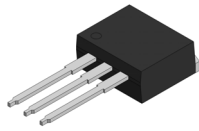
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>D<sup>2</sup>PAK-3 (TO-263, 3-LEAD)</b>	<b>PAGE 1 OF 1</b>

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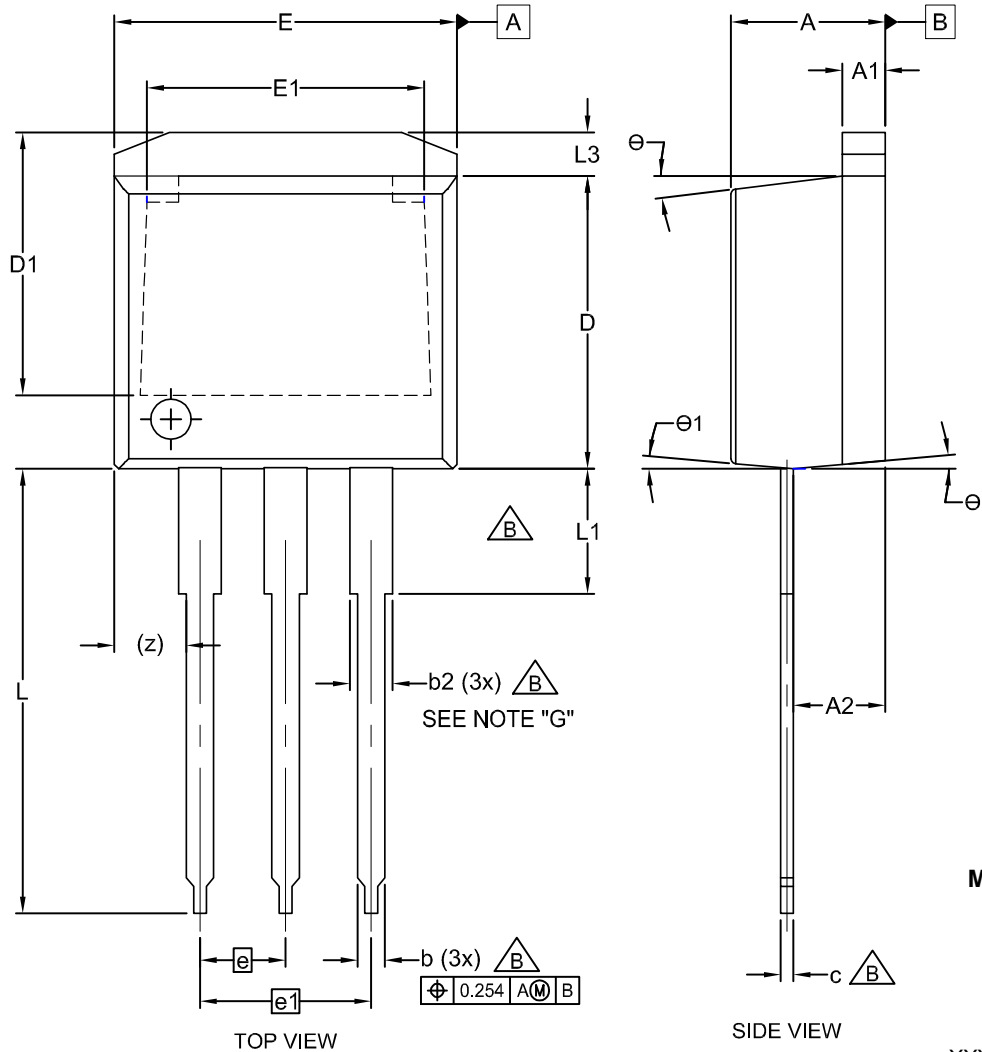
# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS



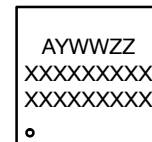
I2PAK (TO-262 3 LD)  
CASE 418AV  
ISSUE A

DATE 30 AUG 2022



DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.06	4.45	4.83
A1	1.14	1.27	1.40
A2	2.03	2.41	2.79
b	0.64	0.77	0.90
b2	1.14	1.46	1.78
c	0.33	0.49	0.64
D	8.64	9.15	9.65
D1	6.86	7.37	7.88
E	9.65	9.97	10.29
E1	6.22	7.28	8.33
e	2.54 BSC		
e1	5.08 BSC		
L	12.70	13.72	14.73
L1	2.80	3.38	3.96
L3	1.00	1.20	1.40
z	2.13 REF		
θ	0°	--	7°
θ1	0°	--	5°

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

#### NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO TO262 JEDEC VARIATION AA.
- B. DOES NOT COMPLY JEDEC STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ANSI Y14.5-1994.
- F. LOCATION OF PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF PACKAGE)
- G. MAXIMUM WIDTH FOR F102 DEVICE = 1.35 MAX.

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<b>DESCRIPTION:</b>	<b>I2PAK (TO-262 3 LD)</b>	<b>PAGE 1 OF 1</b>

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